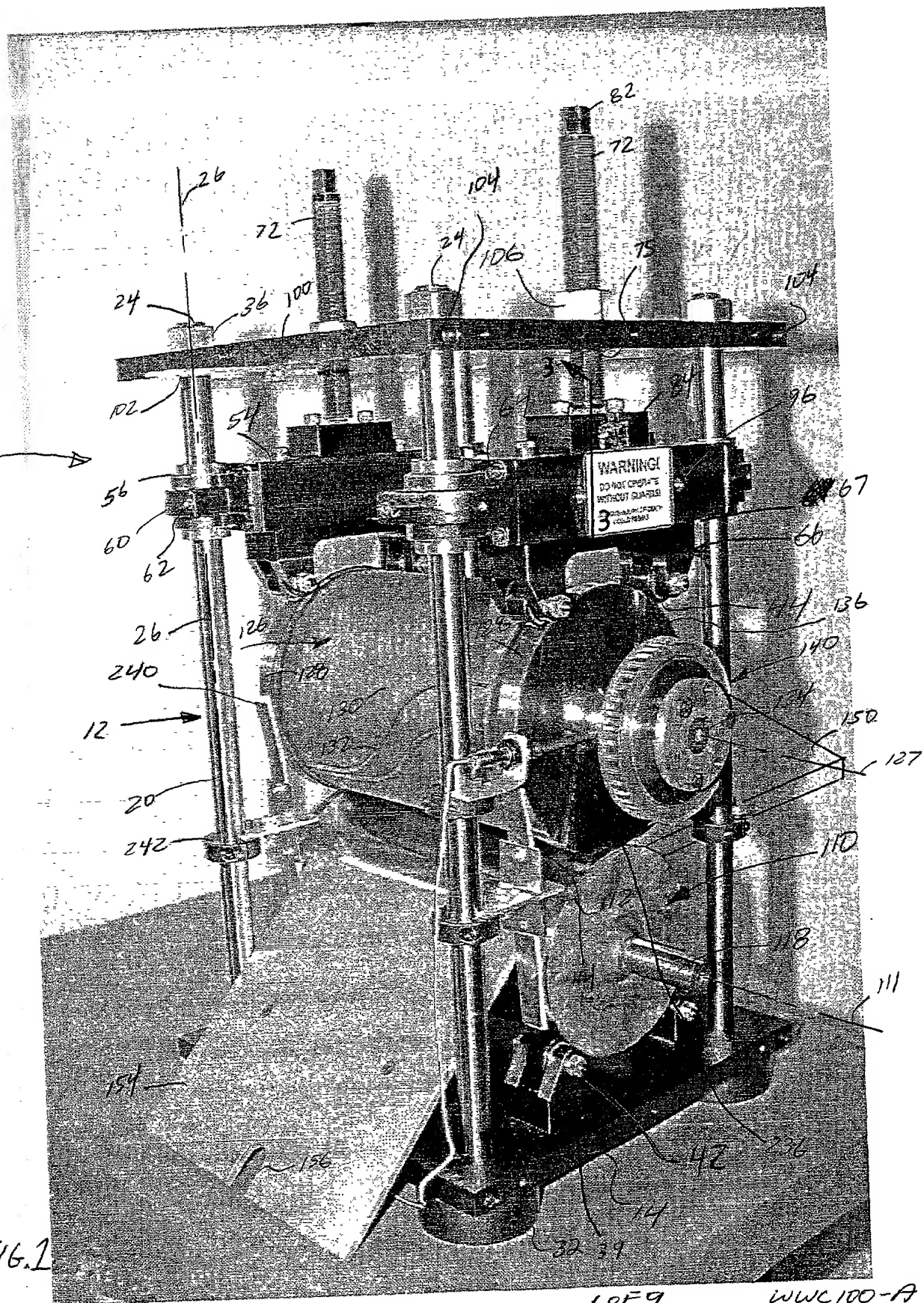


03863431 038634

10 →

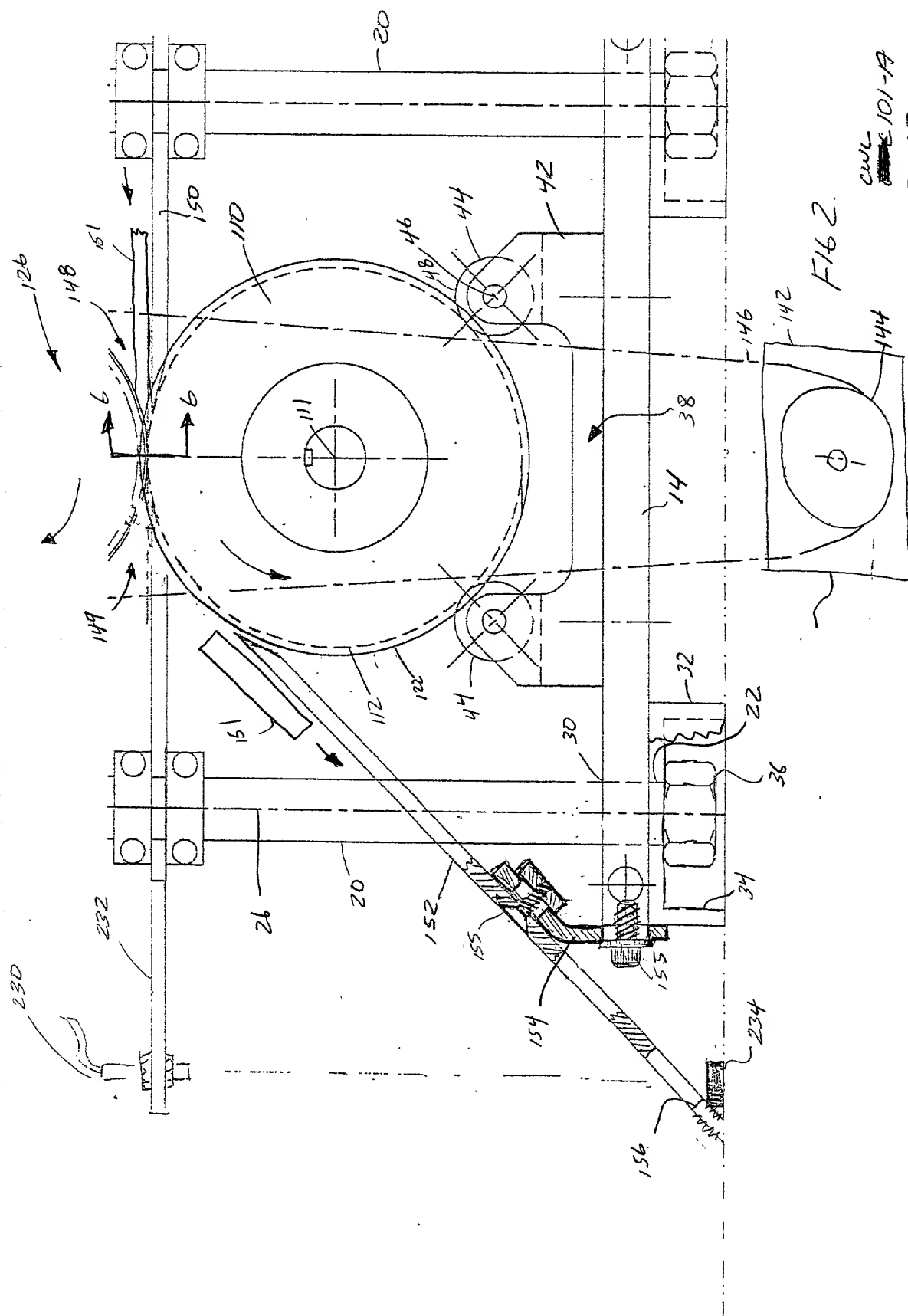
12 →

FIG. 1



10F9

WWC100-A



6702
A-101-17
CWL

1. The present invention relates to a method of forming a
 2. thin layer of material on a substrate, and more particularly
 3. to a method of forming a thin layer of material on a substrate
 4. by the use of a plasma discharge.

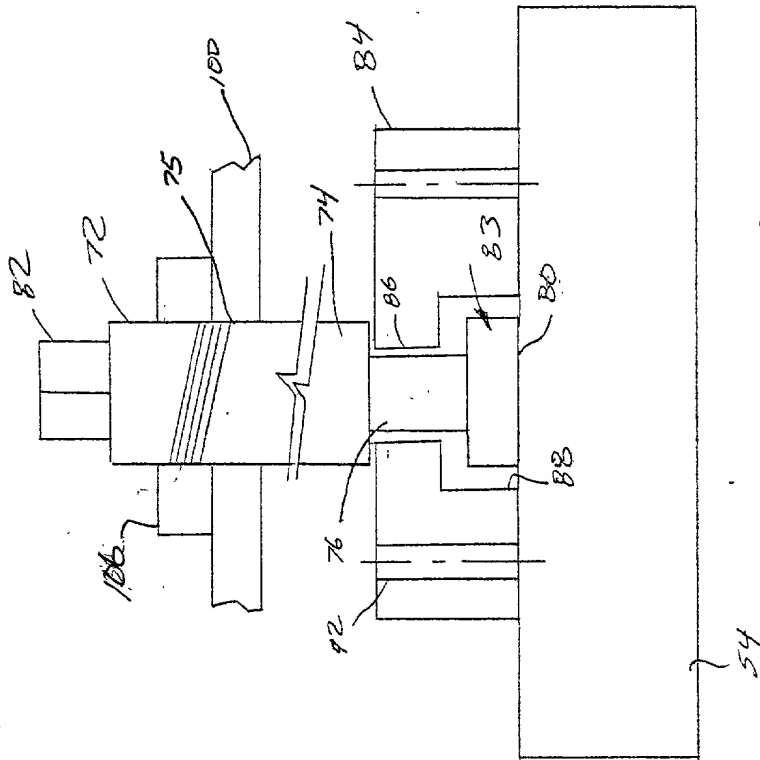


FIG. 3

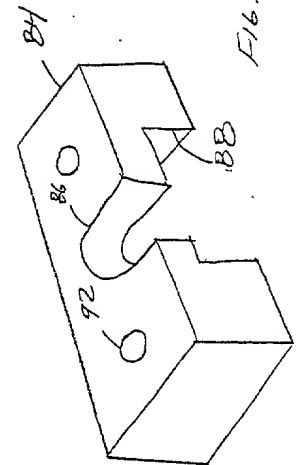


FIG. 4

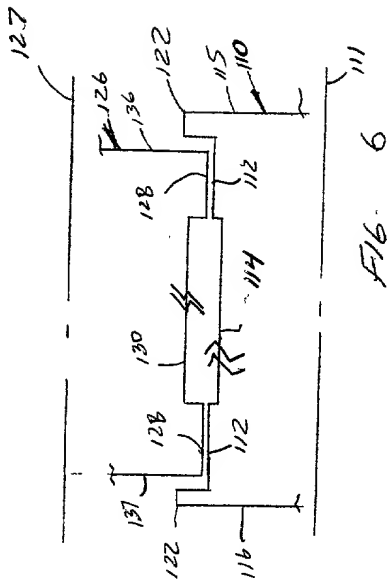


FIG. 6

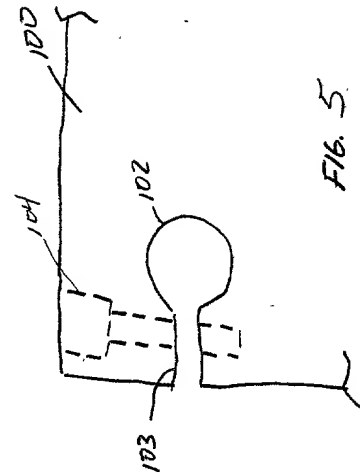


FIG. 5

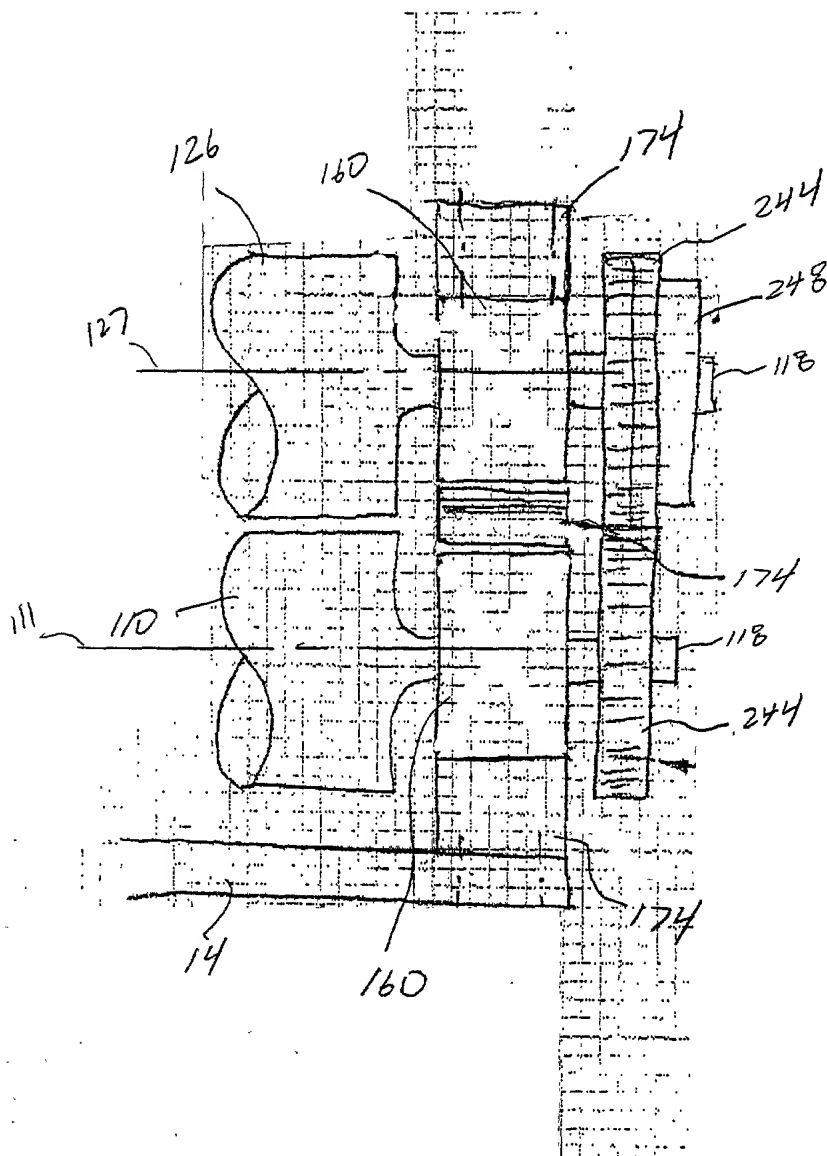
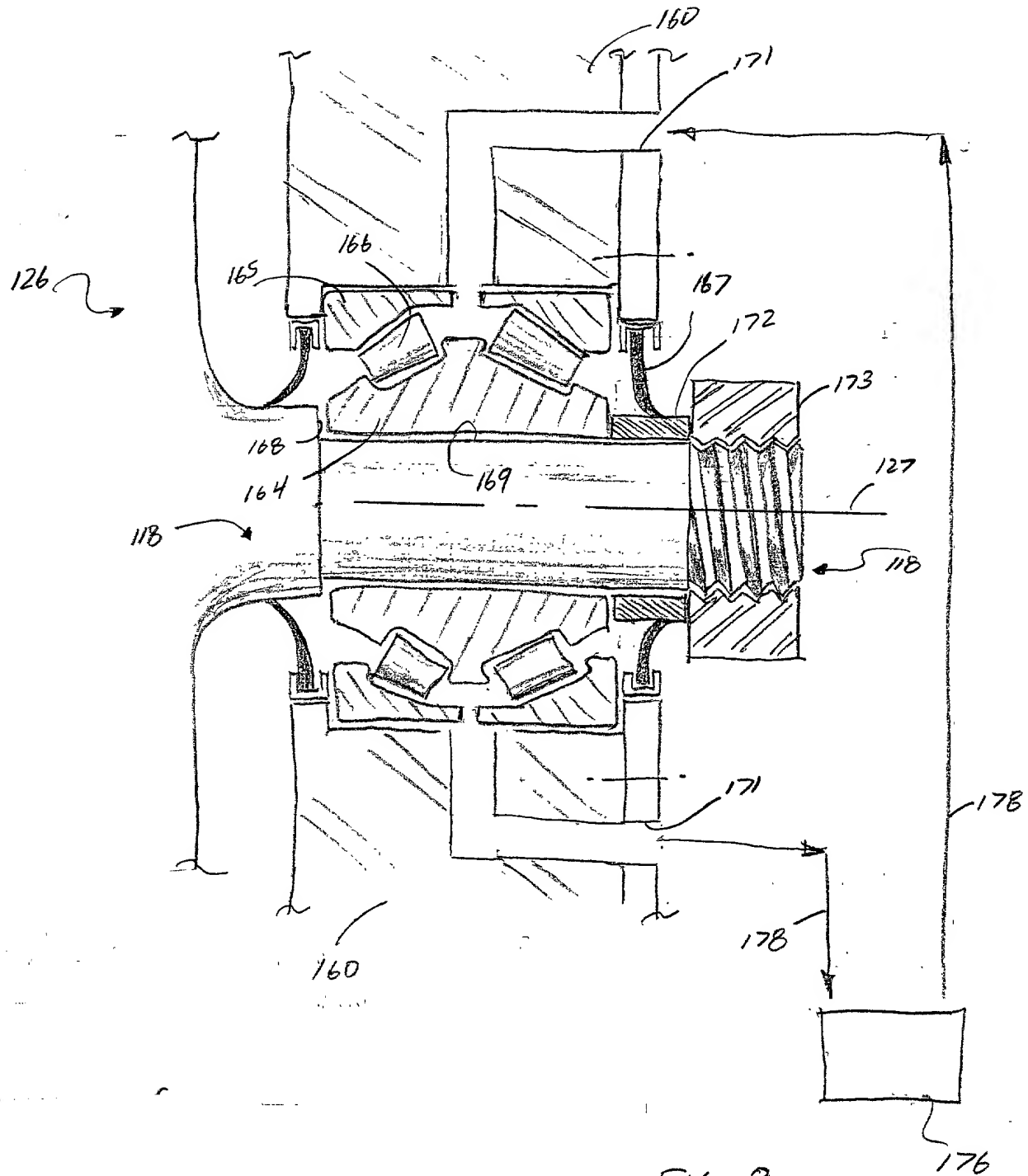


FIG. 8

5 OF 9

CWLIDIA



CWLIDIA
6 OF 9

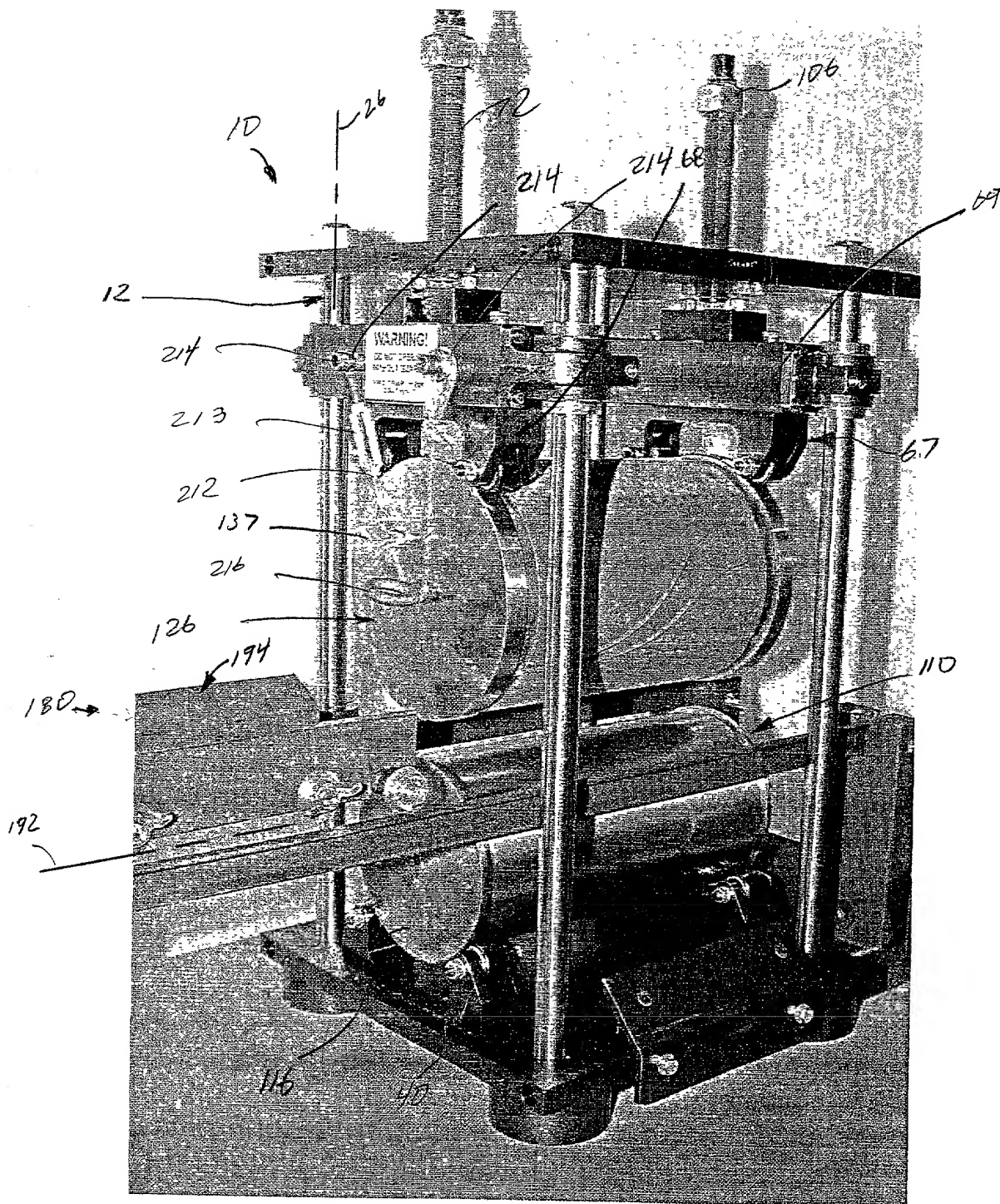


FIG. 10

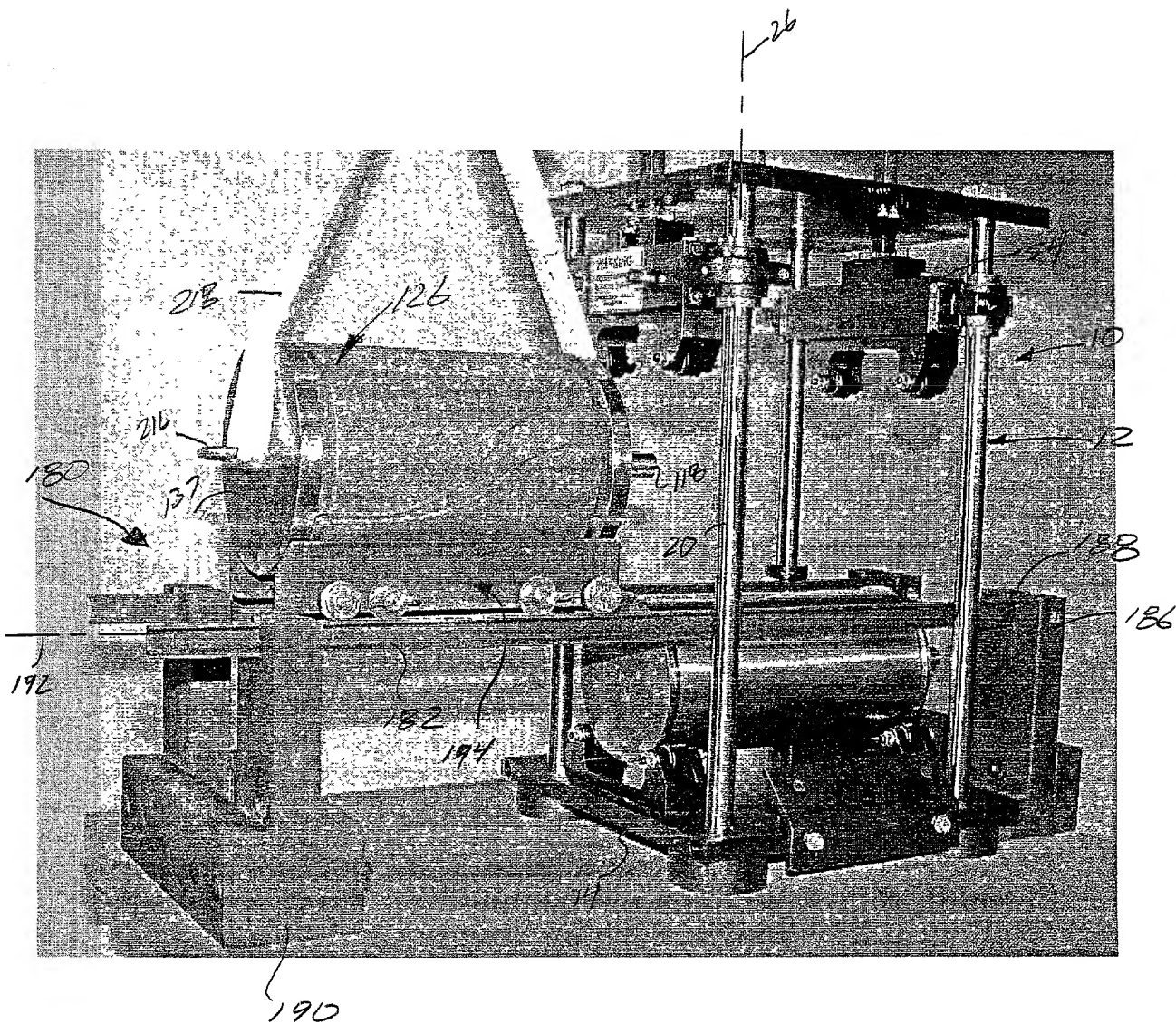


Fig. 11

80F9

CWL100-A.

